

	Type	Hits	Search Text	DBs	Time Stamp
1	BRS	1910	257/724	USPAT; JPO	2002/08/ 08 12:36
2	BRS	24	257/724 and packaged near (chip or die or semiconductor or IC) and (unpacked or bare) near (chip or die or semiconductor or IC) and wire and solder	USPAT; JPO	2002/08/ 08 12:49
3	BRS	255	packaged near (chip or die or semiconductor or IC) and (unpacked or bare) near (chip or die or semiconductor or IC) and wire and solder	USPAT; JPO	2002/08/ 08 13:30
4	BRS	1	"4929999".PN.	USPAT	2002/08/ 08 13:23
5	BRS	1	"5714252".PN.	USPAT	2002/08/ 08 13:23
6	BRS	1	"5874780".PN.	USPAT	2002/08/ 08 13:23
7	BRS	1	"6037044".PN.	USPAT	2002/08/ 08 13:24
8	BRS	204	flip near (chip or die or semiconductor or IC) with solder adj (ball or bump) and (chip or die or semiconductor or IC) near wire and substrate with solder near (ball or bump)	USPAT; US-PGPUB ; EPO; JPO; DERWENT; IBM_TDB	2002/08/ 08 13:34

	Type	Hits	Search Text	DBs	Time Stamp
9	BRS	33	flip near (chip or die or semiconductor or IC) with solder adj (ball or bump) and ((chip or die or semiconductor or IC) near wire with (mold\$3 or encapsul\$5)) and substrate with solder near (ball or bump)	USPAT; US-PGPUB ; EPO; JPO; DERWENT; IBM_TDB	2002/08/ 08 13:46
10	BRS	21	flip near (chip or die or semiconductor or IC) with solder adj (ball or bump) and ((chip or die or semiconductor or IC) near wire with (mold\$3 or encapsul\$5)) and board with solder near (ball or bump)	USPAT; US-PGPUB ; EPO; JPO; DERWENT; IBM_TDB	2002/08/ 08 13:49
11	BRS	173	flip near (chip or die or semiconductor or IC) with solder adj (ball or bump) and ((chip or die or semiconductor or IC) with wire with (mold\$3 or encapsul\$5)) and (board or substrate) with solder near (ball or bump)	USPAT; US-PGPUB ; EPO; JPO; DERWENT; IBM_TDB	2002/08/ 08 14:10
12	BRS	1	"4256532".PN.	USPAT	2002/08/ 08 14:08
13	BRS	1	"5880017".PN.	USPAT	2002/08/ 08 14:08

	Type	Hits	Search Text	DBs	Time Stamp
14	BRS	774	((chip or die or semiconductor or IC) with solder adj (ball or bump)) and ((chip or die or semiconductor or IC) with wire with (mold\$3 or encapsul\$5)) and (board or substrate) with solder near (ball or bump)	USPAT; US-PGPUB ; EPO; JPO; DERWENT; IBM_TDB	2002/08/ 08 15:11
15	BRS	277	(257/723 or 257/731 or 257/685 or 257/778) and ((chip or die or semiconductor or IC) with solder) and ((chip or die or semiconductor or IC) with wire with (mold\$3 or encapsul\$5)) and ((board or substrate) with solder near (ball or bump))	USPAT; US-PGPUB ; EPO; JPO; DERWENT; IBM_TDB	2002/08/ 08 15:31
16	BRS	282	(257/780 or 257/784 or 257/787) and ((chip or die or semiconductor or IC) with solder) and ((chip or die or semiconductor or IC) with wire with (mold\$3 or encapsul\$5)) and ((board or substrate) with solder near (ball or bump))	USPAT; US-PGPUB ; EPO; JPO; DERWENT; IBM_TDB	2002/08/ 08 15:45

	Type	Hits	Search Text	DBs	Time Stamp
17	BRS	21	(257/780 or 257/784 or 257/787) and ((chip or die or semiconductor or IC) with solder) and ((chip or die or semiconductor or IC) with wire with (mold\$3 or encapsul\$5)) and ((module) with solder near (ball or bump))	USPAT; US-PGPUB ; EPO; JPO; DERWENT; IBM_TDB	2002/08/ 08 15:51
18	BRS	61	((chip or die or semiconductor or IC) with solder) and ((chip or die or semiconductor or IC) with wire with (mold\$3 or encapsul\$5)) and ((module) with solder near (ball or bump))	USPAT; US-PGPUB ; EPO; JPO; DERWENT; IBM_TDB	2002/08/ 11 19:39
19	BRS	1	"5222014".PN.	USPAT	2002/08/ 11 19:21
20	BRS	1	"5801072".PN.	USPAT	2002/08/ 11 19:22
21	BRS	1	"5804004".PN.	USPAT	2002/08/ 11 19:22
22	BRS	1	"5994166".PN.	USPAT	2002/08/ 11 19:22
23	BRS	1	"6166443".PN.	USPAT	2002/08/ 11 19:23
24	BRS	1	"5994166".PN.	USPAT	2002/08/ 11 19:23
25	BRS	1	"4954878".PN.	USPAT	2002/08/ 11 19:23
26	BRS	1	"5099306".PN.	USPAT	2002/08/ 11 19:23
27	BRS	1	"5109320".PN.	USPAT	2002/08/ 11 19:23
28	BRS	1	"5128831".PN.	USPAT	2002/08/ 11 19:24
29	BRS	1	"5222014".PN.	USPAT	2002/08/ 11 19:24
30	BRS	1	"5252857".PN.	USPAT	2002/08/ 11 19:24
31	BRS	1	"5291061".PN.	USPAT	2002/08/ 11 19:24

	Type	Hits	Search Text	DBs	Time Stamp
32	BRS	1	"5300801".PN.	USPAT	2002/08/11 19:24
33	BRS	1	"5323060".PN.	USPAT	2002/08/11 19:24
34	BRS	1	"5403784".PN.	USPAT	2002/08/11 19:24
35	BRS	1	"5422435".PN.	USPAT	2002/08/11 19:24
36	BRS	1	"5434745".PN.	USPAT	2002/08/11 19:24
37	BRS	1	"5466627".PN.	USPAT	2002/08/11 19:24
38	BRS	1	"5473814".PN.	USPAT	2002/08/11 19:24
39	BRS	1	"5477082".PN.	USPAT	2002/08/11 19:25
40	BRS	1	"5481134".PN.	USPAT	2002/08/11 19:26
41	BRS	1	"5494841".PN.	USPAT	2002/08/11 19:26
42	BRS	1	"5495398".PN.	USPAT	2002/08/11 19:26
43	BRS	1	"5496775".PN.	USPAT	2002/08/11 19:26
44	BRS	1	"5498902".PN.	USPAT	2002/08/11 19:26
45	BRS	1	"5498905".PN.	USPAT	2002/08/11 19:27
46	BRS	1	"5506756".PN.	USPAT	2002/08/11 19:27
47	BRS	1	"5508565".PN.	USPAT	2002/08/11 19:27
48	BRS	1	"5512765".PN.	USPAT	2002/08/11 19:27
49	BRS	1	"5512780".PN.	USPAT	2002/08/11 19:28
50	BRS	1	"5513076".PN.	USPAT	2002/08/11 19:28
51	BRS	1	"5535101".PN.	USPAT	2002/08/11 19:28
52	BRS	1	"5594275".PN.	USPAT	2002/08/11 19:28
53	BRS	1	"5639696".PN.	USPAT	2002/08/11 19:28
54	BRS	1	"5705858".PN.	USPAT	2002/08/11 19:28
55	BRS	1	"5715144".PN.	USPAT	2002/08/11 19:29
56	BRS	1	"5728606".PN.	USPAT	2002/08/11 19:29

	Type	Hits	Search Text	DBs	Time Stamp
57	BRS	1	"5729440".PN.	USPAT	2002/08/ 11 19:29
58	BRS	13	(packag\$3 near (chip or die or semiconductor or IC) with solder) and ((chip or die or semiconductor or IC) with wire with (mold\$3 or encapsul\$5)) and ((module) with solder near (ball or bump))	USPAT; US-PGPUB ; EPO; JPO; DERWENT; IBM_TDB	2002/08/ 11 20:16
59	BRS	0	"6208525" and ((chip or die or semiconductor or IC) with solder) and ((chip or die or semiconductor or IC) and wire and (mold\$3 or encapsul\$5)) and ((module) and solder near (ball or bump))	USPAT; US-PGPUB ; EPO; JPO; DERWENT; IBM_TDB	2002/08/ 11 19:47
60	BRS	0	6208525.pn. and ((chip or die or semiconductor or IC) with solder) and ((chip or die or semiconductor or IC) and wire and (mold\$3 or encapsul\$5)) and (solder near (ball or bump))	USPAT; US-PGPUB ; EPO; JPO; DERWENT; IBM_TDB	2002/08/ 11 19:48
61	BRS	0	6208525.pn. and ((chip or die or semiconductor or IC) and solder) and ((chip or die or semiconductor or IC) and wire and (mold\$3 or encapsul\$5)) and (solder near (ball or bump))	USPAT; US-PGPUB ; EPO; JPO; DERWENT; IBM_TDB	2002/08/ 11 19:48

	Type	Hits	Search Text	DBs	Time Stamp
62	BRS	0	6208525.pn. and (chip or die or semiconductor or IC) and ((chip or die or semiconductor or IC) and wire and (mold\$3 or encapsul\$5)) and (solder near (ball or bump))	USPAT; US-PGPUB ; EPO; JPO; DERWENT; IBM_TDB	2002/08/ 11 19:48
63	BRS	2159	(packag\$3 near (chip or die or semiconductor or IC)) and ((chip or die or semiconductor or IC) and wire and (mold\$3 or encapsul\$5)) and (solder near (ball or bump))	USPAT; US-PGPUB ; EPO; JPO; DERWENT; IBM_TDB	2002/08/ 11 19:51
64	BRS	904	(packag\$3 near (chip or die or semiconductor or IC)) and ((chip or die or semiconductor or IC) with wire with (mold\$3 or encapsul\$5)) and (solder near (ball or bump))	USPAT; US-PGPUB ; EPO; JPO; DERWENT; IBM_TDB	2002/08/ 11 19:53
65	BRS	526	(packag\$3 near (chip or die or semiconductor or IC)) and ((chip or die or semiconductor or IC) with wire with (mold\$3 or encapsul\$5)) and ((module or substrate) with solder near (ball or bump))	USPAT; US-PGPUB ; EPO; JPO; DERWENT; IBM_TDB	2002/08/ 11 20:02
66	BRS	8	"6157080"	USPAT; US-PGPUB ; EPO; JPO; DERWENT; IBM_TDB	2002/08/ 11 20:09

	Type	Hits	Search Text	DBs	Time Stamp
67	BRS	1	"5008733".PN.	USPAT	2002/08/11 20:04
68	BRS	1	"5210938".PN.	USPAT	2002/08/11 20:04
69	BRS	1	"5385869".PN.	USPAT	2002/08/11 20:04
70	BRS	1	"5640052".PN.	USPAT	2002/08/11 20:04
71	BRS	1	"5697148".PN.	USPAT	2002/08/11 20:04
72	BRS	1	"5844320".PN.	USPAT	2002/08/11 20:04
73	BRS	1	"5889326".PN.	USPAT	2002/08/11 20:04
74	BRS	12	"6208525"	USPAT; US-PGPUB ; EPO; JPO; DERWENT; IBM_TDB	2002/08/11 20:09
75	BRS	1	"4929999".PN.	USPAT	2002/08/11 20:11
76	BRS	1	"5714252".PN.	USPAT	2002/08/11 20:11
77	BRS	1	"5874780".PN.	USPAT	2002/08/11 20:12
78	BRS	1	"6037044".PN.	USPAT	2002/08/11 20:12
79	BRS	13	(packag\$3 near (chip or die or semiconductor or IC)) and ((chip or die or semiconductor or IC) with wire with (resin)) and ((module or MCM) with solder near (ball or bump))	USPAT; US-PGPUB ; EPO; JPO; DERWENT; IBM_TDB	2002/08/11 20:39

	Type	Hits	Search Text	DBs	Time Stamp
80	BRS	121	(packaged near (chip or die or semiconductor or IC)) and ((chip or die or semiconductor or IC) with wire with (mold\$3 or encapsulat\$3 or resin)) and ((substrate or module or MCM) with solder near (ball or bump))	USPAT; US-PGPUB ; EPO; JPO; DERWENT; IBM_TDB	2002/08/ 11 20:59
81	BRS	0	"5872051" and (packaged near (chip or die or semiconductor or IC)) and ((chip or die or semiconductor or IC) with wire with (mold\$3 or encapsulat\$3 or resin)) and ((substrate or module or MCM) with solder near (ball or bump))	USPAT; US-PGPUB ; EPO; JPO; DERWENT; IBM_TDB	2002/08/ 11 21:01
82	BRS	3	"5872051" and (packaged near (chip or die or semiconductor or IC)) and ((chip or die or semiconductor or IC) and wire and (mold\$3 or encapsulat\$3 or resin)) and ((substrate or module or MCM) and solder near (ball or bump))	USPAT; US-PGPUB ; EPO; JPO; DERWENT; IBM_TDB	2002/08/ 11 21:02

	Type	Hits	Search Text	DBs	Time Stamp
83	BRS	10	"5872051" and ((chip or die or semiconductor or IC) and ((chip or die or semiconductor or IC) and wire and (mold\$3 or encapsulat\$3 or resin)) and ((substrate or module or MCM) and solder near (ball or bump))	USPAT; US-PGPUB ; EPO; JPO; DERWENT; IBM_TDB	2002/08/ 11 21:39
84	BRS	0	package near module with size same (("5508565".PN. or "5535101".PN. or "5496775".PN. or "5728606".PN. or 6412701.PN.) near (mm))	USPAT; US-PGPUB ; EPO; JPO; DERWENT; IBM_TDB	2002/08/ 11 21:46
85	BRS	0	257/\$.ccls. and module same (("5508565".PN. or "5535101".PN. or "5496775".PN. or "5728606".PN. or 6412701.PN.) near (mm))	USPAT; JPO	2002/08/ 11 22:04
86	BRS	0	(semiconductor or chip or die or IC) and module same (("5508565".PN. or "5535101".PN. or "5496775".PN. or "5728606".PN. or 6412701.PN.) near (mm))	USPAT; JPO	2002/08/ 11 22:19
87	BRS	1301	(semiconductor or chip or die or IC) and module with (mm or millimeter)	USPAT; JPO	2002/08/ 11 22:35
88	BRS	112	(semiconductor or chip or die or IC) and module near (mm or millimeter)	USPAT; JPO	2002/08/ 11 22:44

	Type	Hits	Search Text	DBs	Time Stamp
89	BRS	0	(semiconductor or chip or die or IC) and module same ("5535101".PN. or "5508565".PN. or "5496775".PN. or 37.5 or "5728606".PN. or 6412701.PN. or 42.5) near (mm or millimeter)	USPAT; JPO	2002/08/ 11 22:47
90	BRS	11	(semiconductor or chip or die or IC) and module and ("5535101".PN. or "5508565".PN. or "5496775".PN. or 37.5 or "5728606".PN. or 6412701.PN. or 42.5) near (mm or millimeter)	USPAT; JPO	2002/08/ 11 22:52
91	BRS	0	(semiconductor or chip or die or IC) and module same ("35 times 35" or "31 times 31" or "27 times 27" or "37.5 times 37.5" or "40 times 40" or "42 times 42" or "42.5 times 42.5")	USPAT; JPO	2002/08/ 11 22:57
92	BRS	0	(semiconductor or chip or die or IC) and (module or carrier or MCM) same ("35 times 35" or "31 times 31" or "27 times 27" or "37.5 times 37.5" or "40 times 40" or "42 times 42" or "42.5 times 42.5")	USPAT; JPO	2002/08/ 11 23:03

	Type	Hits	Search Text	DBs	Time Stamp
93	BRS	7	(semiconductor or chip or die or IC) and (module or carrier or MCM) and ("35 times 35" or "31 times 31" or "27 times 27" or "37.5 times 37.5" or "40 times 40" or "42 times 42" or "42.5 times 42.5")	USPAT; JPO	2002/08/ 11 23:35
94	BRS	4	5872051.pn. or 6376907.pn. or 6157080.pn. or 6208525.pn. or 20020017721.pn. or 20020074669.pn.	USPAT; JPO	2002/08/ 11 23:37